

and the hot dip solder plating layer are formed on one but not both of a top and a bottom side of the lid.

44. A portion to be soldered of an electronic part as claimed in claim 24 wherein the substrate is an iron-nickel alloy, and the electroplated layer and the hot dip solder plating layer are formed on one but not both of a top and a bottom side of the lid.

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45. A method as claimed in claim 36 wherein the hot dip solder plating layer has a thickness of 15 - 40 micrometers, and the electroplated layer and the hot dip solder plating layer are formed on one but not both of a top and a bottom side of the lid.

46. A method as claimed in claim 36 wherein the difficult to solder material is an iron-nickel alloy, and the electroplated layer and the hot dip solder plating layer are formed on one but not both of a top and a bottom side of the lid.

47. A method as claimed in claim 42 wherein the hot dip solder plating layer has a thickness of 15 - 40 micrometers, and the electroplated layer and the hot dip solder plating layer are formed on one but not both of a top and a bottom side of the lid.

48. A method as claimed in claim 42 wherein the difficult to solder material is an iron-nickel alloy, and the electroplated layer and the hot dip solder plating layer are formed on one but

not both of a top and a bottom side of the lid.

49. A method as claimed in claim 25 wherein the difficult to solder material comprises a continuous plate, the method including:

forming the electroplated layer and the hot dip solder plating layer on one but not both of a top and a bottom side of the continuous plate; and

c) punching the continuous plate after forming the hot dip solder plating layer to obtain preplated parts.

50. A method as claimed in claim 49 including punching the plate to form preplated lids for semiconductor packages.

51. A method as claimed in claim 49 wherein the hot dip solder plating layer has a thickness of 15 - 40 micrometers.

52. A method as claimed in claim 49 wherein the plate comprises an iron-nickel alloy.

REMARKS

In response to the Official Action mailed on October 30, 2002, the application has been amended. No new matter has been added. Reconsideration of the rejections of the claims is respectfully requested in view of the above amendments and the following remarks.